



EV077384995-29/supl  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

supl

WDN-03-02

**RESPONSE TO DECEMBER 26, 2001 FINAL OFFICE ACTION**  
**RESPONSE TO ACCOMPANY RCE FILING**

To: Box RCE  
Assistant Commissioner for Patents  
Washington, D.C. 20231

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TECHNOLOGY CENTER R3700

Responsive to the Final Office Action dated December 26, 2001,  
Applicant amends and remarks as follows:

**AMENDMENTS**